

S1ZB60

600V 0.8A

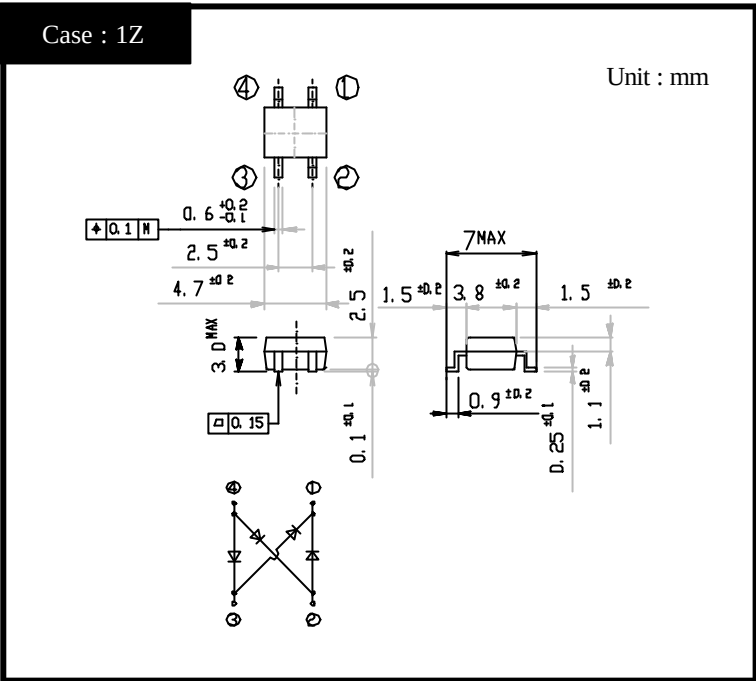
FEATURES

- Small SMT package
- High reliability with superior moisture resistance
- Applicable to Automatic Insertion

APPLICATION

- Switching power supply
- Home Appliances, Office Equipment
- Telecommunication, Factory Automation

OUTLINE DIMENSIONS



RATINGS

● Absolute Maximum Ratings (If not specified Tl=25°C)

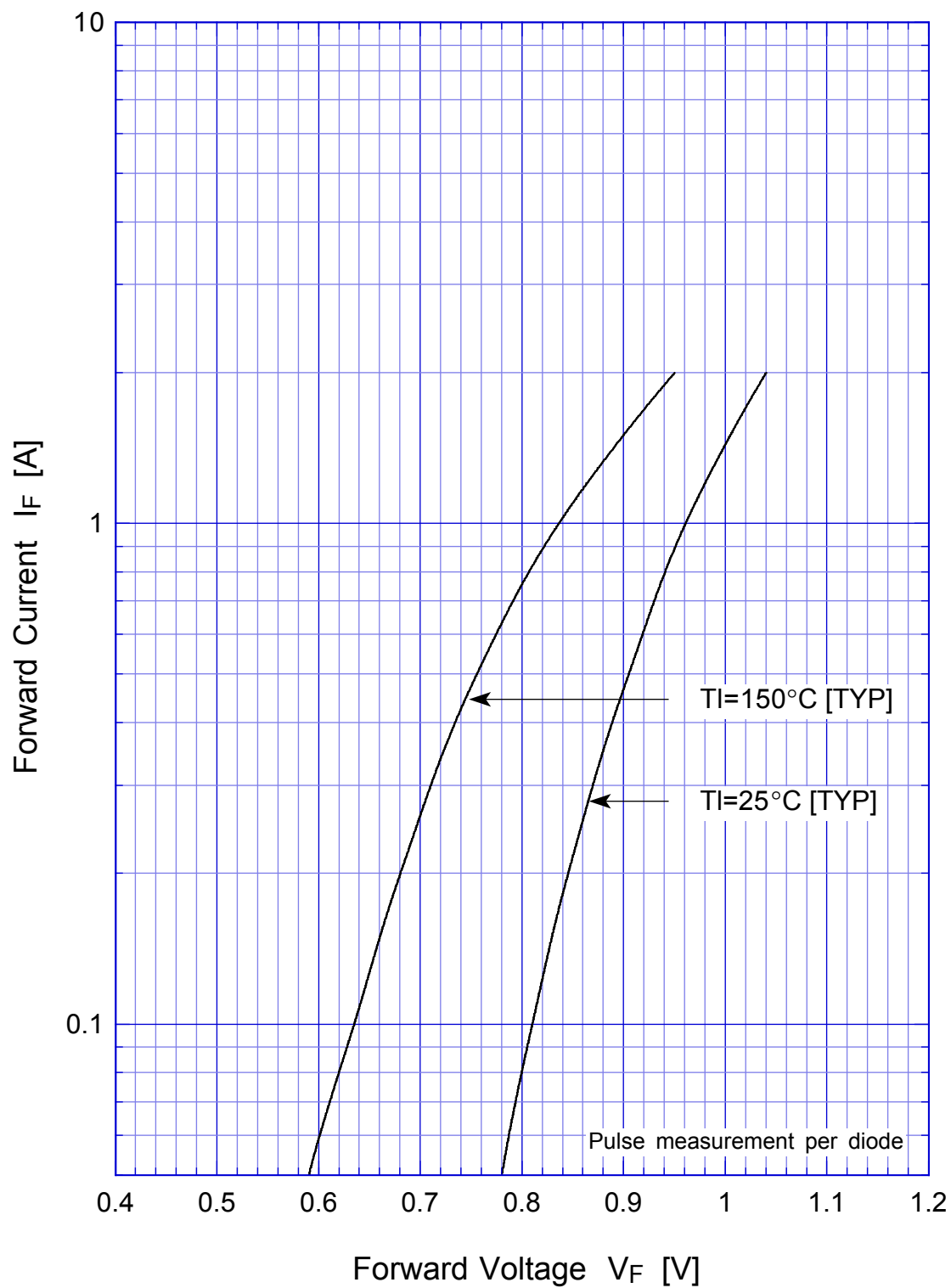
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	Tstg		-40~150	°C
Operating Junction Temperature	Tj		150	°C
Maximum Reverse Voltage	V _{RM}		600	V
Average Rectified Forward Current	I _O	50Hz sine wave, R-load On alumina substrate Ta=25°C	0.8	A
		50Hz sine wave, R-load On glass-epoxy substrate Ta=25°C	0.5	
Peak Surge Forward Current	I _{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, Tj=25°C	30	A
Current Squared Time	I ² t	1ms ≤ t < 10ms Tj=25°C	4.5	A ² s

● Electrical Characteristics (If not specified Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Forward Voltage	V _F	I _F =0.4A, Pulse measurement, Rating of per diode	Max.1.05	V
Reverse Current	I _R	V _R =V _{RM} , Pulse measurement, Rating of per diode	Max.10	μA
Thermal Resistance	θ _{jl}	junction to lead	Max.20	°C/W
	θ _{ja}	junction to ambient On alumina substrate	Max.76	
	θ _{ja}	junction to ambient On glass-epoxy substrate	Max.134	

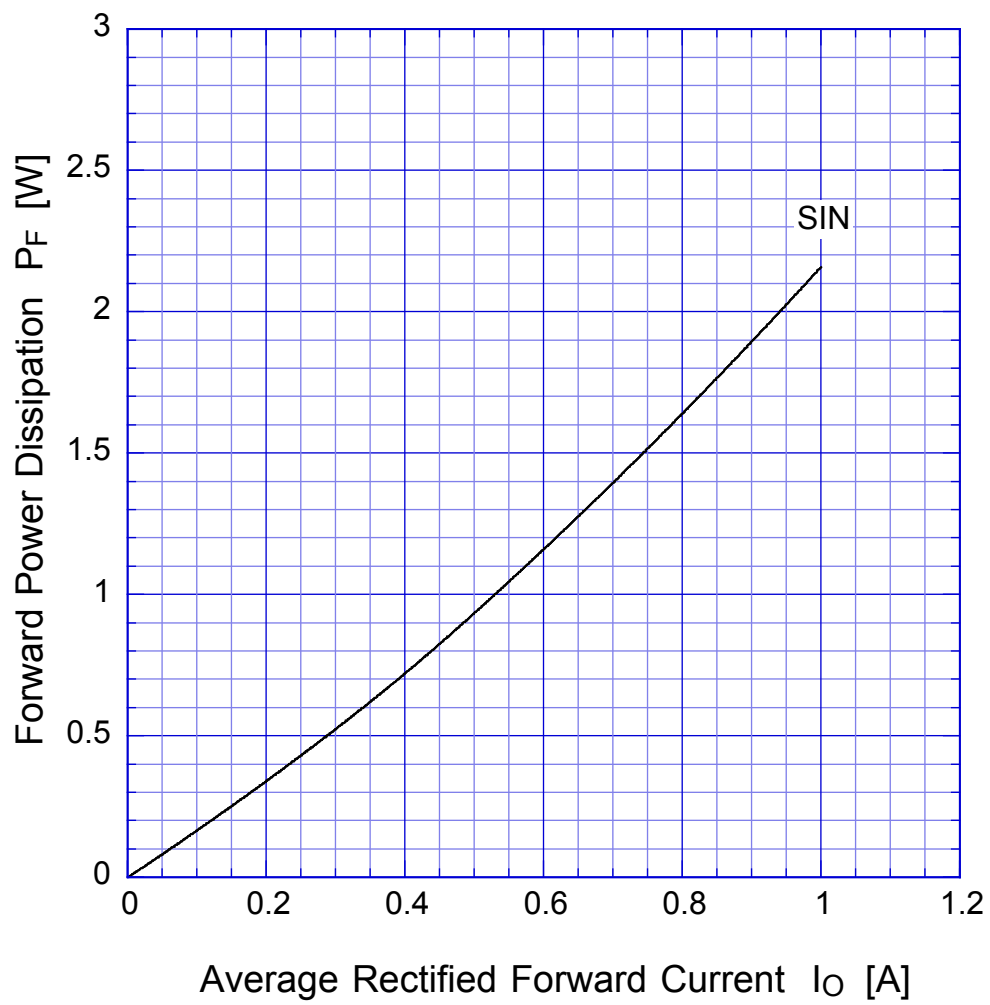
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Forward Voltage



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Forward Power Dissipation

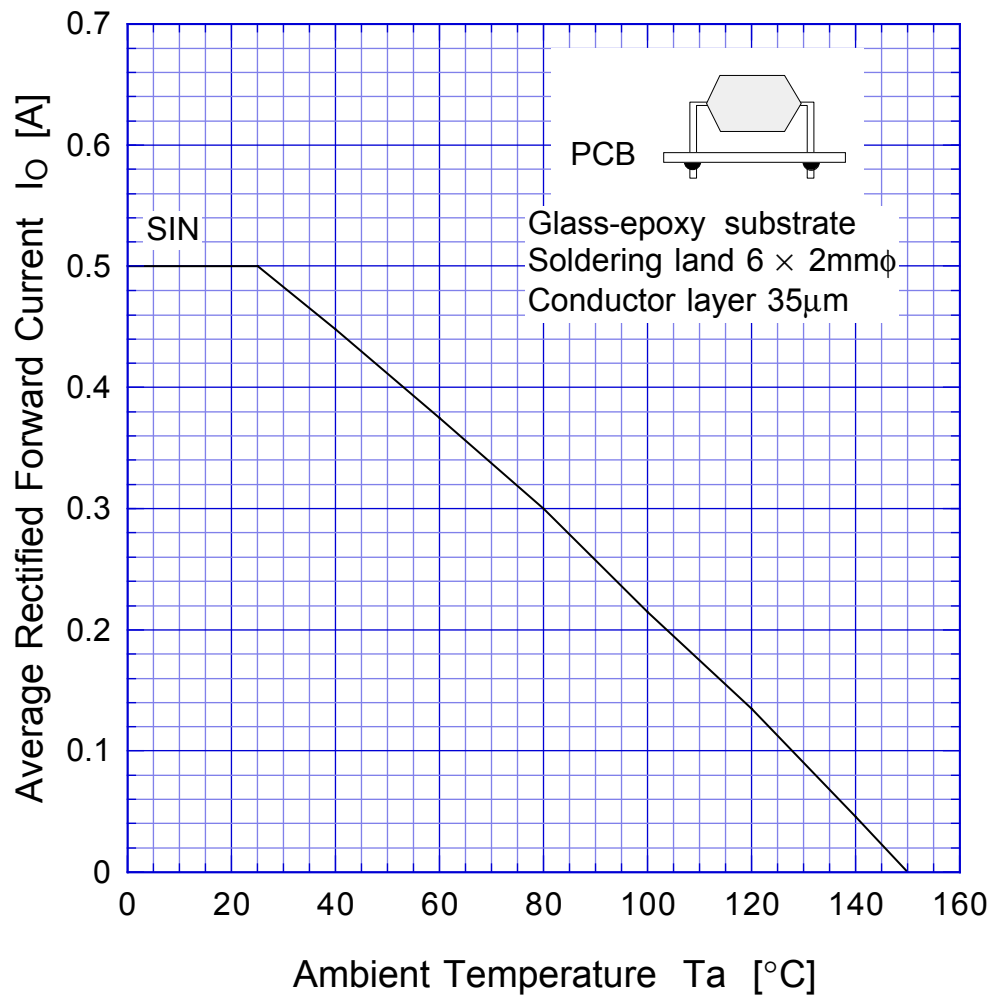


$T_j = 150^\circ\text{C}$

Sine wave

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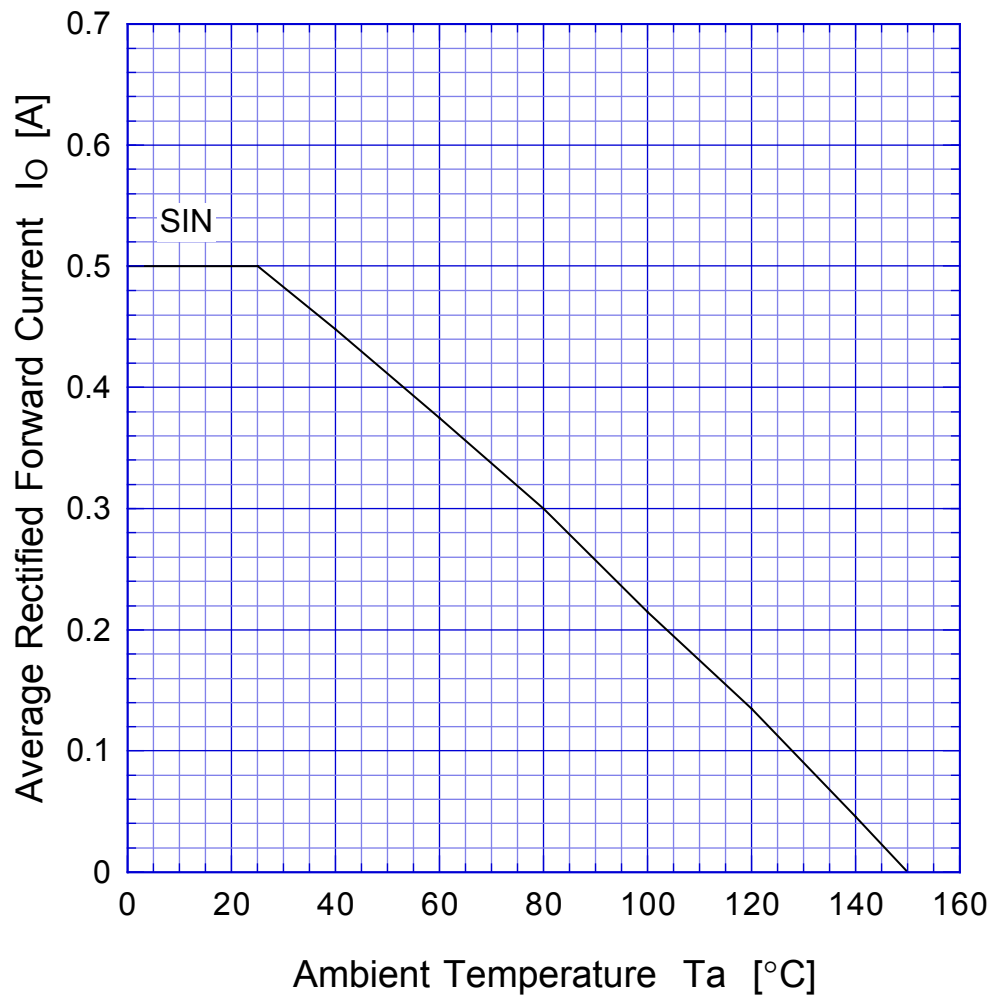
Derating Curve



Sine wave
R-load
Free in air

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Derating Curve



Sine wave
R-load
Free in air

	Glass-epoxy	Alumina
Soldering land	1mmφ	1mmφ
Conductor layer	35μm	20μm
Substrate thickness		0.64mm

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Peak Surge Forward Capability

